

Amendments to the Claims:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

Listing of Claims:

1. (Currently Amended) A connection board comprising an insulating resin composition layer formed of ~~one layer or two or more layers~~ at least one sub-layer and a connection conductor which is formed so as to pass through the insulating resin composition layer in its thickness direction at least at a position where a conductor circuit is connected, wherein the connection conductor is all made of a metal.

2. (Original) The connection board according to claim 1 further comprising a conductor circuit which is electrically connected to the connection conductor for at least one surface of the connection board.

3. (Original) The connection board according to claim 2, wherein the conductor circuit is a metallic layer.

4. (Original) The connection board according to any one of claims 1 to 3, wherein an exposed portion of the connection conductor is covered with metal.

5. (Currently Amended) The connection board according to any one of claims 1 to 3, wherein ~~one at least one~~ at least one sub-layer of the insulating resin composition ~~composition layer~~, placed at at least one of front and rear outermost layers of the ~~connection board is or both of them are~~ insulating resin composition layer, is mainly made of thermoplastic resin.

6. - 49. (Cancelled).

50. (New) The connection board according to claim 1, wherein at least one sub-layer of the insulating resin composition layer, which is at least one of a front surface layer and a rear surface layer of the insulating resin composition layer, contains a liquid crystal polymer.

51. (New) The connection board according to claim 1, wherein said insulating resin composition layer includes at least two sub-layers.

52. (New) The connection board according to claim 50, wherein the liquid crystal polymer has 180°C or higher of phase transition temperature from smectic phase to nematic phase.

53. (New) The connection board according to claim 50, wherein the liquid crystal polymer has 280°C or higher of phase transition temperature from smectic phase to nematic phase.

54. (New) The connection board according to claim 1, wherein the connection conductor is etching a metallic layer of copper.

55. (New) The connection board according to claim 4, wherein the connection conductor is covered with one or more selected from the group consisting of copper, indium, zinc, lead, gold, platinum, nickel, palladium, tin, and alloys thereof.

56. (New) The connection board according to claim 4, wherein the connection conductor is covered with metallic film formed by a method of performing electroless copper plating subsequent to application of palladium, copper sputtering or copper sputtering with chromium being a base, print of silver paste, substituted or

electroless gold plating, electrolysis or electroless plating of nickel/gold, electrolysis or electroless plating of nickel/palladium/gold, or electrolysis or electroless plating of tin or tin alloy.

57. (New) The connection board according to claim 1, wherein said connection conductor is a solid all-metal member.

58. (New) The connection board according to claim 1, wherein a surface of the connection conductor is exposed through at least one surface of the insulating resin composition layer in the thickness direction of the insulating resin composition layer, and the exposed surface of the connection conductor is covered with a metal layer.

59. (New) The connection board according to claim 58, wherein surfaces of the connection conductor are exposed through both surfaces of the insulating resin composition layer in the thickness direction, and the exposed surfaces of the connection conductor are covered with metal layers.